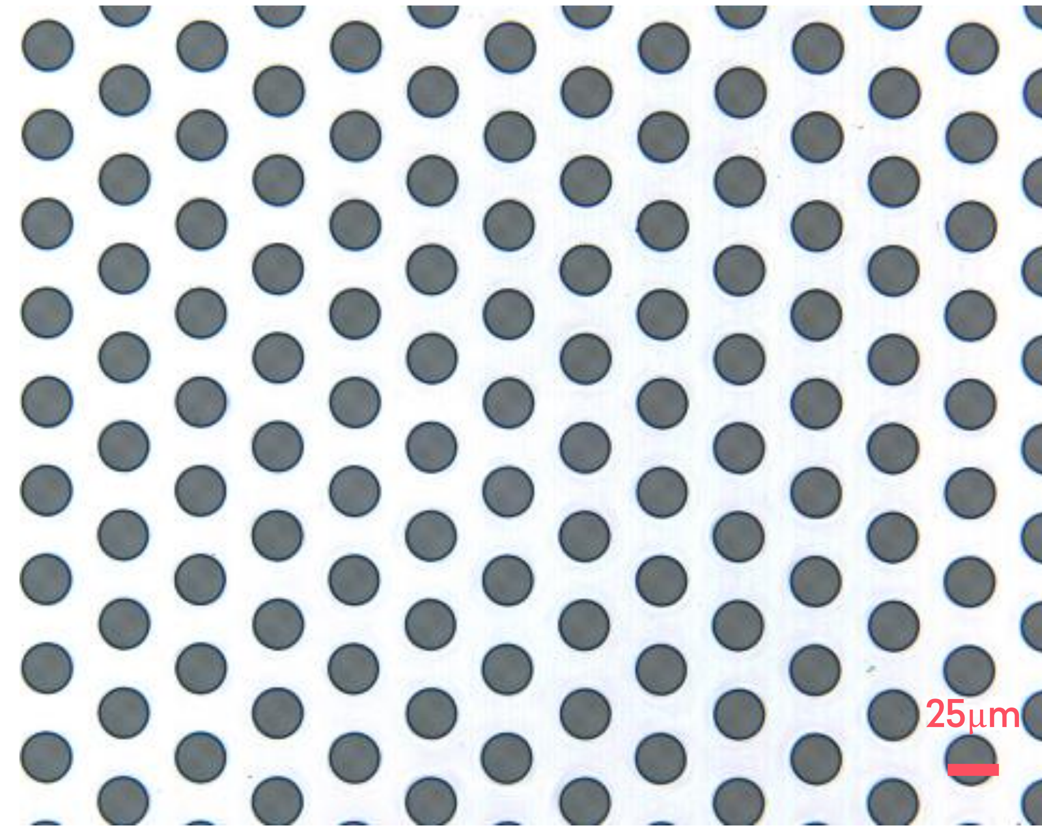
WORKSHOP OF PHOTONICS

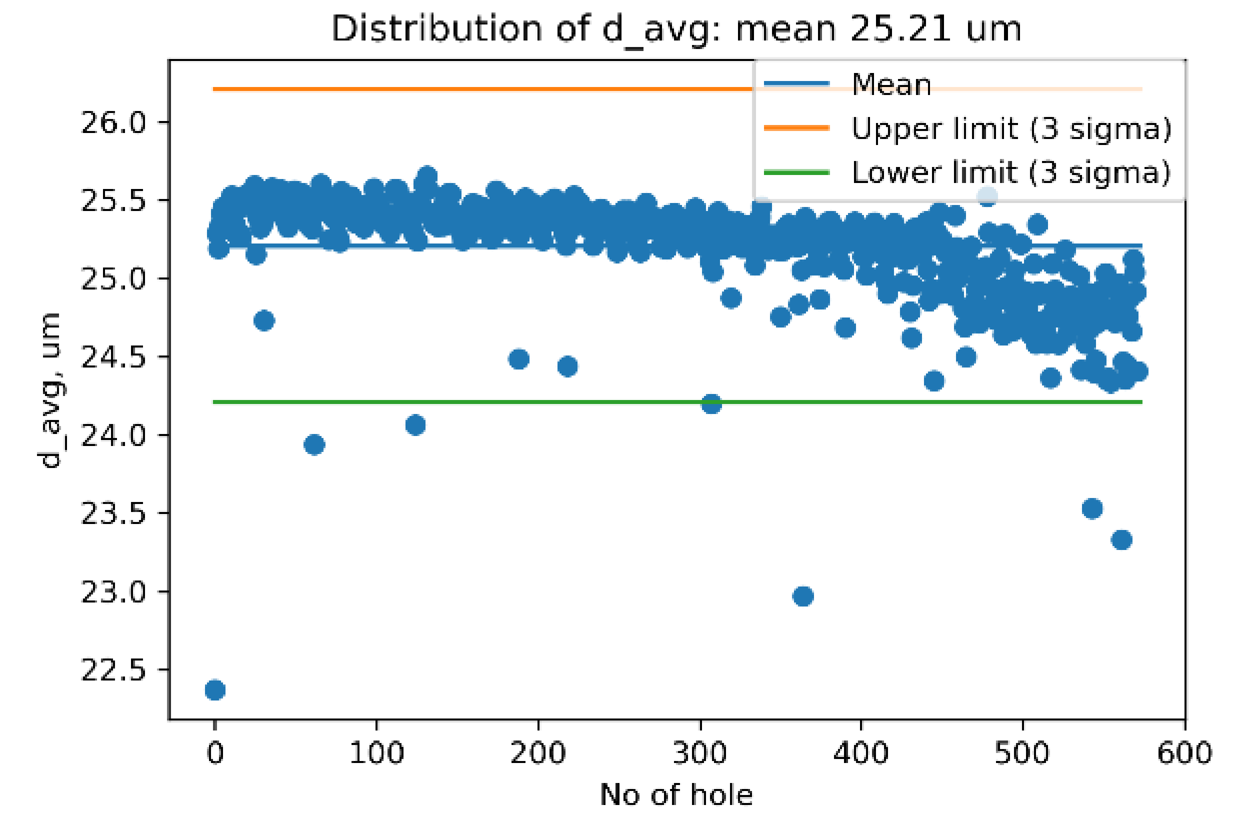
Through glass via TGV wafers

Ultra-high quality microholes in glass

99% identical

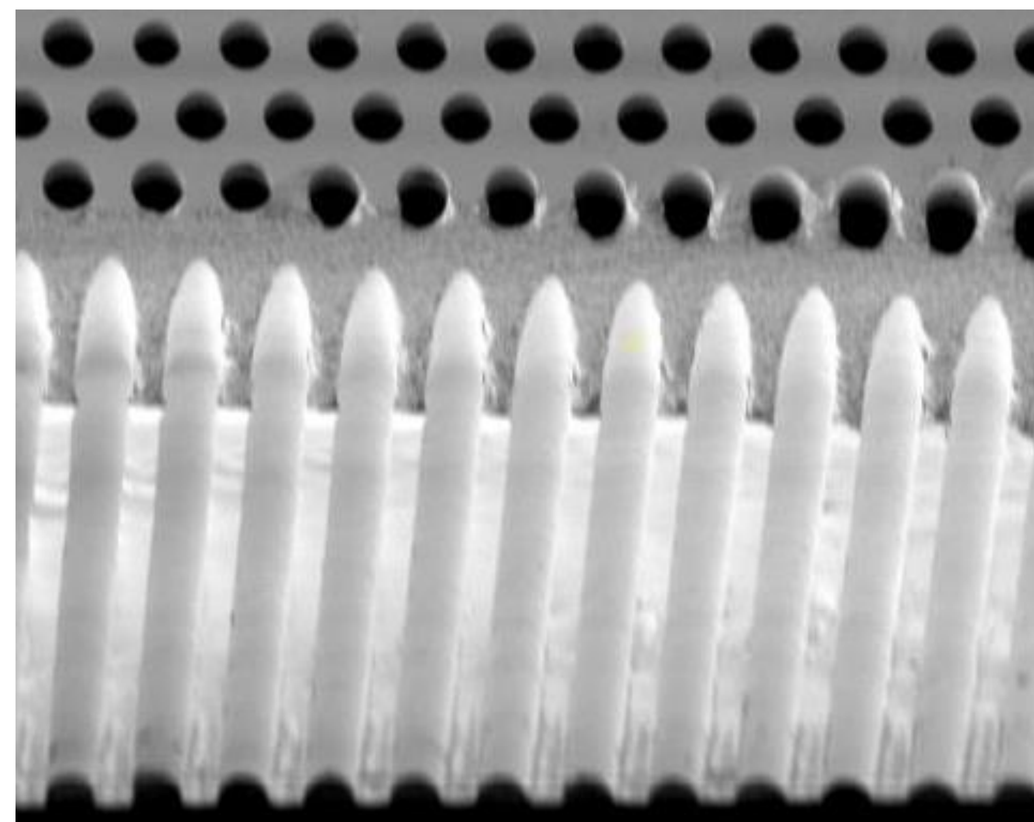
diameter holes

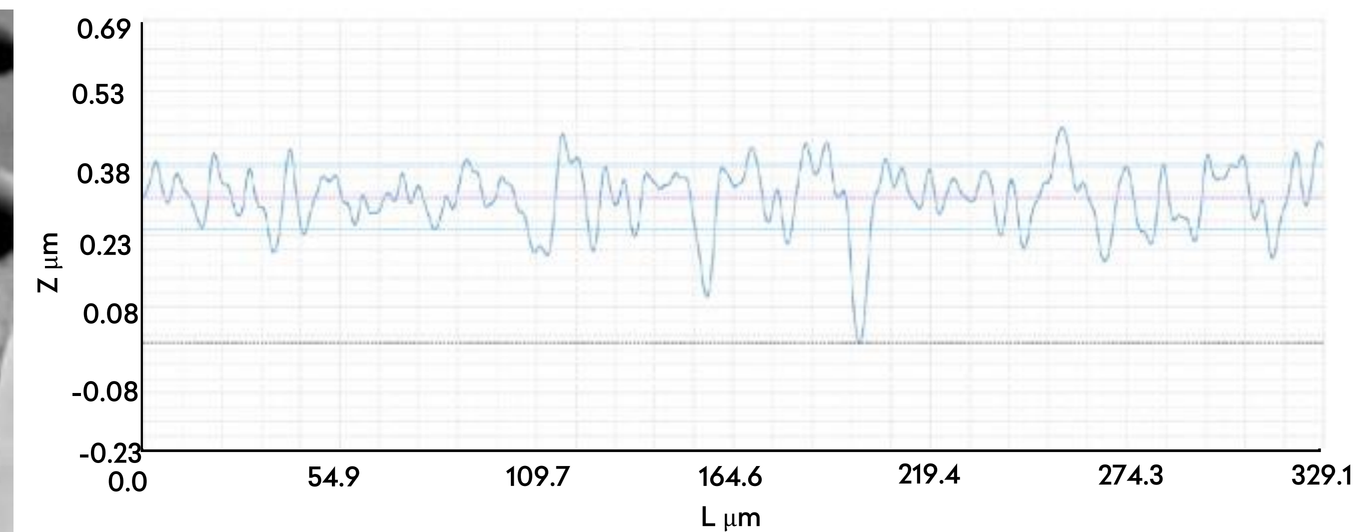




Ra <0.08 µm

super smooth sidewalls





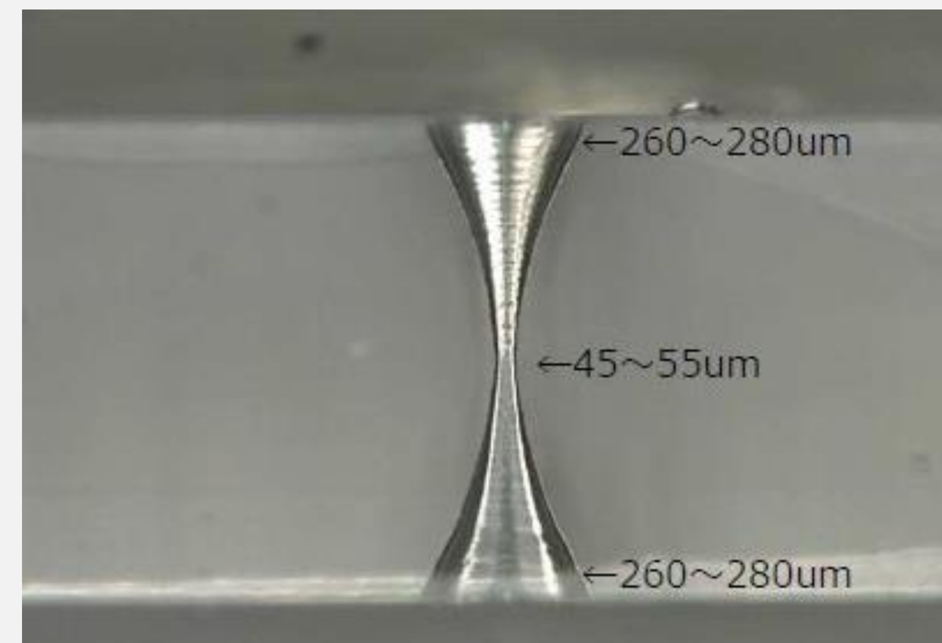
www.wophotonics.com

Features

- Custom design
- High speed
- Glass Thickness: <1,1 mm
- Wafer sizes: all standard up to 200 mm
- Microhole diameter up to 10 µm
- Positional accuracy ±3 µm
- No chipping
- No micro cracks
- High aspect ratios – up to 1:100
- Hole type - through via, blind via
- Hole shape - hourglass

No chipping or micro cracks

HIGH SPEED: 45 min., takt time.
3 M holes in 200 mm diameter and 500 µm thickness fused silica wafer.



Hole shape - hourglass